



**Product Change Notification / ALAN-23OACF570**

---

**Date:**

01-Jul-2024

**Product Category:**

OTN Processors & PHYs

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 6405 Final Notice: Qualification of SR1 as an additional substrate material for PM6010B1-FEI, PM6011B1-FEI, PM6017B1-FEI, and PM6018B1-FEI catalog part numbers (CPN) available in 1932L BBGA (45x45x4.00mm) package.

**Affected CPNs:**

[ALAN-23OACF570\\_Affected\\_CPN\\_07012024.pdf](#)

[ALAN-23OACF570\\_Affected\\_CPN\\_07012024.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of SR1 as an additional substrate material for PM6010B1-FEI, PM6011B1-FEI, PM6017B1-FEI, and PM6018B1-FEI catalog part numbers (CPN) available in 1932L BBGA (45x45x4.00mm) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change
--	------------	-------------

Assembly Site	Amkor Technology Korea (K4), INC (ATK)	Amkor Technology Korea (K4), INC (ATK)	Amkor Technology Korea (K4), INC (ATK)
Core Material	E705G	E705G	E705G
Substrate Material	SR7300GR-B	SR7300GR-B	SR1
Substrate Material Thickness	21±7.5um	21±7.5um	21±10um
Process	ABF GZ-41	ABF GZ-41	ABF GL 102
Bump Material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag
Die Attach Material	SCF-5	SCF-5	SCF-5
Underfill Material	NAU-39	NAU-39	NAU-39

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying an additional SR1 substrate material.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**July 30, 2024 (date code: 2431)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	July 2023					>	July 2024				
	27	28	29	30	31		27	28	29	30	31
Initial PCN Issue Date				x							
Qual Report Availability							x				
Final PCN Issue Date							x				
Estimated Implementation Date											x

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**July 27, 2023: Issued initial notification.

July 01, 2024: Issued final notification. Updated the notification subject, description of change and affected parts list to remove CPN PM6015B1-FEI. Attached the Qualification Report. Provided estimated first ship date to be on July 30, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachments:

[PCN\\_ALAN-230ACF570 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.